

AMENDMENTS TO THE SPECIFICATION

Please amend the specification as shown following:

In the paragraph beginning on page 6, line 25:

FIG.3 is a cross sectional view showing a light emitting apparatus 1 in the first preferred embodiment of the invention. The light emitting apparatus 1 is composed of: lead frames 2A and 2C of metallic material; a cup 2B that is formed on the tip of the lead frame 2A to house a LED chip 3; a transparent structure 5 that is bonded to the LED chip 3 through light transmitting adhesive layer 4; Ag paste 6 that fixes the transparent structure 5 to the bottom of cup 2B; bonding wires 7 that electrically connects between the electrodes of LED chip 5 3 and the lead frames 2A, 2C; light transmitting resin 8 that is filled in the cup 2B to seal the LED chip 3 and transparent structure 5; and transparent epoxy resin 9 that integrally molds the lead frames 2A, ~~2A~~ 2C, and bonding wires 7.

In the paragraph beginning on page 8, line 10:

FIG.4 is a cross sectional view showing part of the light emitting apparatus in the first embodiment. In FIG.4, light transmitting resin 8 around the LED ~~chip~~ chip 3 is omitted. The LED chip 3 is composed of: sapphire substrate 3A; Al buffer layer 3B; n-type semiconductor layer 3C; n-electrode 3D; p-type semiconductor layer 3E; multiple layers 3F including light emitting layer; and p-electrode 3G. Bonding wires 7 are bonded to the n-electrode 3D and p-electrode 3G. The n-electrode 3D and p-electrode 3G each have such a thickness that light does not transmit through.